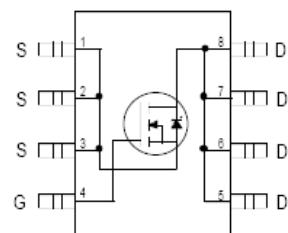
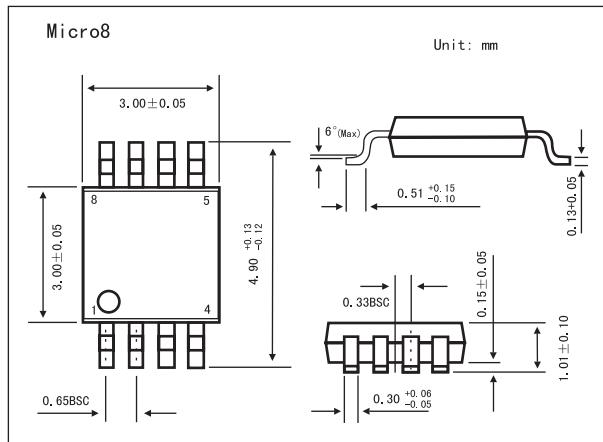


HEXFET® Power MOSFET

KRF7603

■ Features

- Generation V Technology
- Ultra Low On-Resistance
- N-Channel MOSFET
- Very Small SOIC Package
- Low Profile (<1.1mm)
- Available in Tape & Reel
- Fast Switching



Top View

■ Absolute Maximum Ratings Ta = 25°C

Parameter	Symbol	Rating	Unit
Continuous Drain Current, Vgs @ 4.5V, TA = 25°C	Id	5.6	A
Continuous Drain Current, Vgs @ 4.5V, TA = 70°C	Id	4.5	
Pulsed Drain Current*1	Idm	30	
Power Dissipation Ta = 25°C *1	Pd	1.8	W
Linear Derating Factor		14	W/°C
Gate-to-Source Voltage	Vgs	±20	V
Peak Diode Recovery dv/dt*1	dv/dt	5	V/ns
Junction and Storage Temperature Range	Tj, Tstg	-55 to + 150	°C
Junction-to-Ambient *2	Rθ JA	70	°C/W

* Id ≤ 3.7A, di/dt ≤ 130A/μs, VDD ≤ V(BR)DSS, TJ ≤ 150°C

*2 Surface mounted on FR-4 board, t ≤ 10sec.

KRF7603

■ Electrical Characteristics Ta = 25°C

Parameter	Symbol	Testconditons	Min	Typ	Max	Unit
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250 μ A	30			V
Breakdown Voltage Temp. Coefficient	△V _{(BR)DSS} /△T _J	I _D = 1mA, Reference to 25°C		0.029		V/°C
Static Drain-to-Source On-Resistance	R _{D(on)}	V _{GS} = 10V, I _D = 3.7A*1		0.035		Ω
		V _{GS} = 4.5V, I _D = 1.9A*1		0.060		
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μ A	1.0			V
Forward Transconductance	g _{fs}	V _{DS} = 10V, I _D = 1.9A*1	4.3			S
Drain-to-Source Leakage Current	I _{DSS}	V _{DS} = 24V, V _{GS} = 0V		1.0		μ A
		V _{DS} = 24V, V _{GS} = 0V, T _J = 125°C		25		
Gate-to-Source Forward Leakage	I _{GSS}	V _{GS} = -20V		-100		nA
Gate-to-Source Reverse Leakage		V _{GS} = 20V		100		
Total Gate Charge	Q _g	I _D = 3.7A V _{DS} = 24V		18	27	nC
Gate-to-Source Charge	Q _{gs}			2.4	3.6	
Gate-to-Drain ("Miller") Charge	Q _{gd}			5.6	8.4	
Turn-On Delay Time	t _{d(on)}	V _{DD} = 15V I _D = 3.7A R _G = 6.2 Ω		5.7		ns
Rise Time	t _r			28		
Turn-Off Delay Time	t _{d(off)}			18		
Fall Time	t _f			12		
Input Capacitance	C _{iss}	V _{GS} = 0V		520		pF
Output Capacitance	C _{oss}	V _{DS} = 25V		200		
Reverse Transfer Capacitance	C _{rss}	f = 1.0MHz		80		
Continuous Source Current (Body Diode)	I _s	MOSFET symbol showing the integral reverse p-n junction diode.			1.8	A
Pulsed Source Current (Body Diode) *2	I _{SM}				30	
Diode Forward Voltage	V _{SD}	T _J = 25°C, I _s = 3.7A, V _{GS} = 0V*1			1.2	V
Reverse Recovery Time	t _{rr}	T _J = 25°C, I _F = 3.7A, V _R = 10V di/dt = 100A/ μ s*1		53	80	ns
Reverse RecoveryCharge	Q _{rr}			87	130	nC

*1 Pulse width ≤ 300μs; duty cycle ≤ 2%.

*2 Repetitive rating; pulse width limited bymax

